



Material Content Data Sheet



Sales Product Name		1EDN7511B		Issued		24. January 2018		
MA#		MA001893956						
Package		PG-SOT23-6-2		Weight*		17.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.383	7.79	7.79	77874	77874
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		123	
	non noble metal	zinc	7440-66-6	0.009	0.05		492	
	non noble metal	iron	7439-89-6	0.175	0.98		9844	
wire	non noble metal	copper	7440-50-8	7.097	39.97	41.01	399708	410167
	noble metal	gold	7440-57-5	0.082	0.46	0.46	4626	4626
	organic material	carbon black	1333-86-4	0.016	0.09		910	
encapsulation	plastics	epoxy resin	-	1.236	6.96		69620	
	inorganic material	silicondioxide	60676-86-0	6.827	38.45	45.50	384502	455032
leadfinish	non noble metal	tin	7440-31-5	0.465	2.62	2.62	26179	26179
plating	noble metal	silver	7440-22-4	0.167	0.94	0.94	9410	9410
tape	plastics	epoxy resin	-	0.148	0.84		8356	
	inorganic material	silicondioxide	60676-86-0	0.148	0.84	1.68	8356	16712
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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